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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

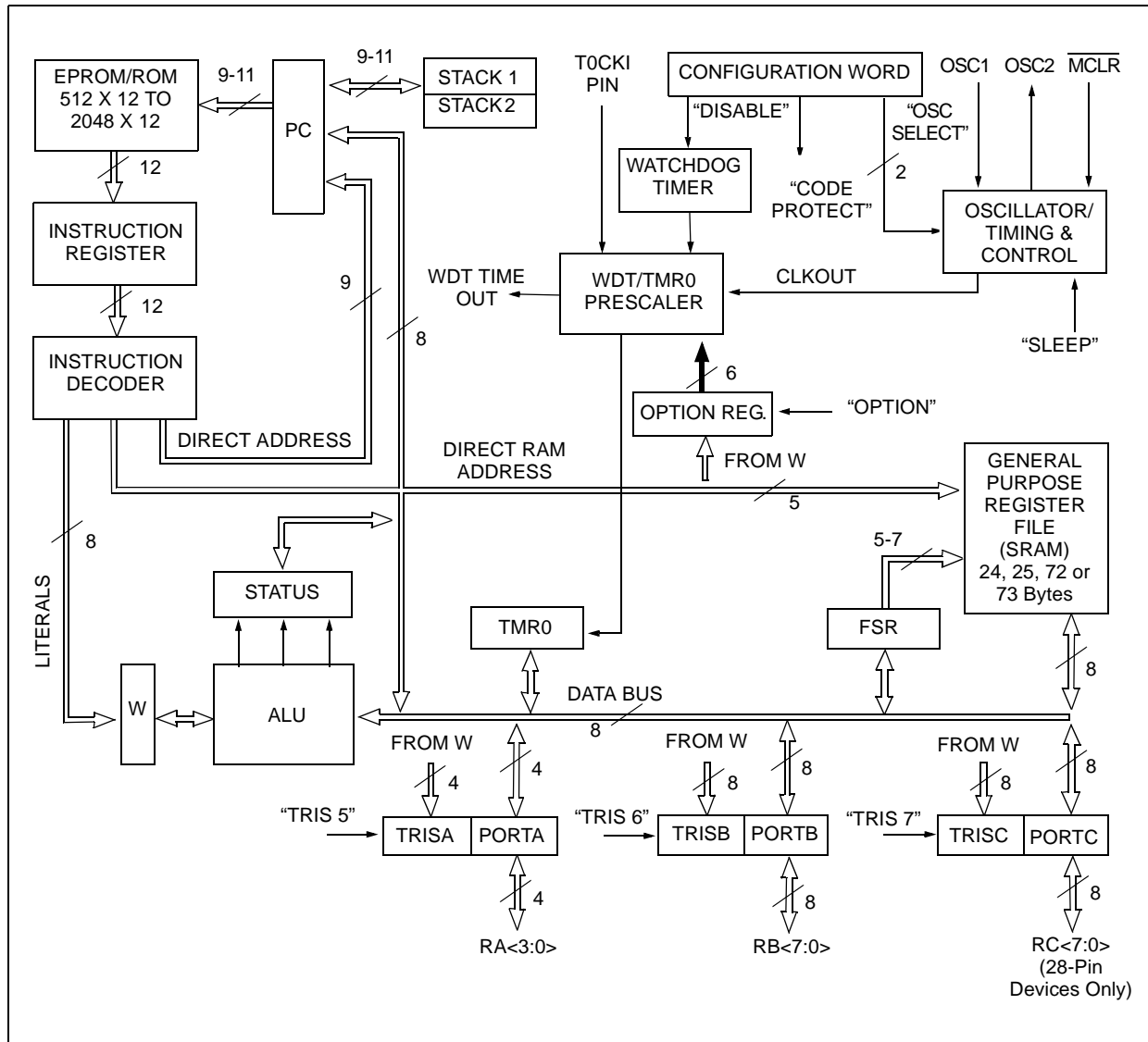
### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	3KB (2K x 12)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	72 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 6.25V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/pic16c57-xti-so">https://www.e-xfl.com/product-detail/microchip-technology/pic16c57-xti-so</a>

# PIC16C5X

**FIGURE 3-1: PIC16C5X SERIES BLOCK DIAGRAM**



# PIC16C5X

**TABLE 3-2: PINOUT DESCRIPTION - PIC16C55, PIC16C57, PIC16CR57**

Pin Name	Pin Number			Pin Type	Buffer Type	Description
	DIP	SOIC	SSOP			
RA0	6	6	5	I/O	TTL	Bi-directional I/O port
RA1	7	7	6	I/O	TTL	
RA2	8	8	7	I/O	TTL	
RA3	9	9	8	I/O	TTL	
RB0	10	10	9	I/O	TTL	Bi-directional I/O port
RB1	11	11	10	I/O	TTL	
RB2	12	12	11	I/O	TTL	
RB3	13	13	12	I/O	TTL	
RB4	14	14	13	I/O	TTL	
RB5	15	15	15	I/O	TTL	
RB6	16	16	16	I/O	TTL	
RB7	17	17	17	I/O	TTL	
RC0	18	18	18	I/O	TTL	Bi-directional I/O port
RC1	19	19	19	I/O	TTL	
RC2	20	20	20	I/O	TTL	
RC3	21	21	21	I/O	TTL	
RC4	22	22	22	I/O	TTL	
RC5	23	23	23	I/O	TTL	
RC6	24	24	24	I/O	TTL	
RC7	25	25	25	I/O	TTL	
T0CKI	1	1	2	I	ST	Clock input to Timer0. Must be tied to Vss or VDD, if not in use, to reduce current consumption.
$\overline{\text{MCLR}}$	28	28	28	I	ST	Master clear (RESET) input. This pin is an active low RESET to the device.
OSC1/CLKIN	27	27	27	I	ST	Oscillator crystal input/external clock source input.
OSC2/CLKOUT	26	26	26	O	—	Oscillator crystal output. Connects to crystal or resonator in crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
VDD	2	2	3,4	P	—	Positive supply for logic and I/O pins.
Vss	4	4	1,14	P	—	Ground reference for logic and I/O pins.
N/C	3,5	3,5	—	—	—	Unused, do not connect.

Legend: I = input, O = output, I/O = input/output, P = power, — = Not Used, TTL = TTL input, ST = Schmitt Trigger input

## 4.4 RC Oscillator

For timing insensitive applications, the RC device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor ( $R_{EXT}$ ) and capacitor ( $C_{EXT}$ ) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low  $C_{EXT}$  values. The user also needs to take into account variation due to tolerance of external R and C components used.

Figure 4-5 shows how the R/C combination is connected to the PIC16C5X. For  $R_{EXT}$  values below 2.2 k $\Omega$ , the oscillator operation may become unstable, or stop completely. For very high  $R_{EXT}$  values (e.g., 1 M $\Omega$ ) the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend keeping  $R_{EXT}$  between 3 k $\Omega$  and 100 k $\Omega$ .

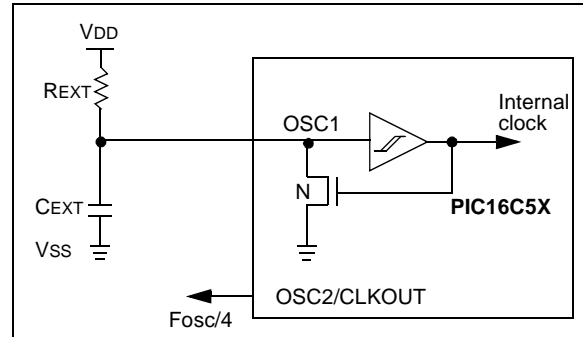
Although the oscillator will operate with no external capacitor ( $C_{EXT} = 0$  pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

The Electrical Specifications sections show RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

Also, see the Electrical Specifications sections for variation of oscillator frequency due to  $V_{DD}$  for given  $R_{EXT}/C_{EXT}$  values as well as frequency variation due to operating temperature for given R, C, and  $V_{DD}$  values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin, and can be used for test purposes or to synchronize other logic.

**FIGURE 4-5: RC OSCILLATOR MODE**



**Note:** If you change from this device to another device, please verify oscillator characteristics in your application.

# PIC16C5X

**TABLE 5-3: RESET CONDITIONS FOR ALL REGISTERS**

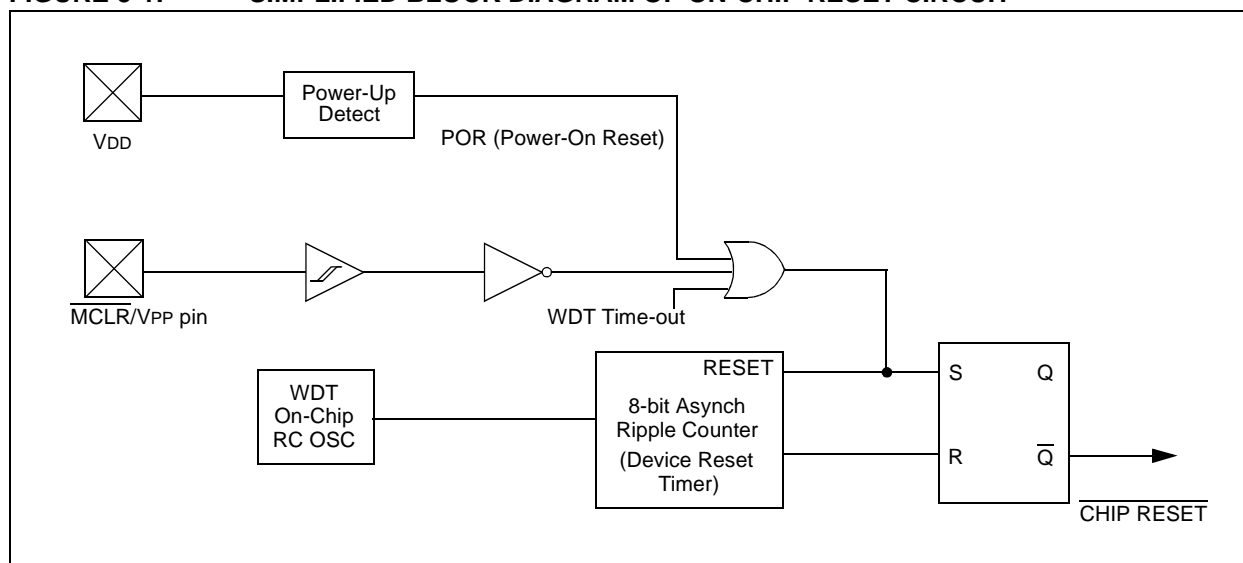
Register	Address	Power-On Reset	MCLR or WDT Reset
W	N/A	xxxx xxxx	uuuu uuuu
TRIS	N/A	1111 1111	1111 1111
OPTION	N/A	--11 1111	--11 1111
INDF	00h	xxxx xxxx	uuuu uuuu
TMR0	01h	xxxx xxxx	uuuu uuuu
PCL	02h	1111 1111	1111 1111
STATUS	03h	0001 1xxx	000q quuu
FSR <sup>(1)</sup>	04h	1xxx xxxx	1uuu uuuu
PORTA	05h	---- xxxx	---- uuuu
PORTB	06h	xxxx xxxx	uuuu uuuu
PORTC <sup>(2)</sup>	07h	xxxx xxxx	uuuu uuuu
General Purpose Register Files	07-7Fh	xxxx xxxx	uuuu uuuu

Legend: x = unknown    u = unchanged    - = unimplemented, read as '0'  
q = see tables in Table 5-1 for possible values.

**Note 1:** These values are valid for PIC16C57/CR57/C58/CR58. For the PIC16C54/CR54/C55/C56/CR56, the value on RESET is 111x xxxx and for MCLR and WDT Reset, the value is 111u uuuu.

**2:** General purpose register file on PIC16C54/CR54/C56/CR56/C58/CR58.

**FIGURE 5-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT**





## 8.0 TIMER0 MODULE AND TMR0 REGISTER

The Timer0 module has the following features:

- 8-bit timer/counter register, TMR0
  - Readable and writable
- 8-bit software programmable prescaler
- Internal or external clock select
  - Edge select for external clock

Figure 8-1 is a simplified block diagram of the Timer0 module, while Figure 8-2 shows the electrical structure of the Timer0 input.

Timer mode is selected by clearing the T0CS bit (OPTION<5>). In Timer mode, the Timer0 module will increment every instruction cycle (without prescaler). If TMR0 register is written, the increment is inhibited for the following two cycles (Figure 8-3 and Figure 8-4). The user can work around this by writing an adjusted value to the TMR0 register.

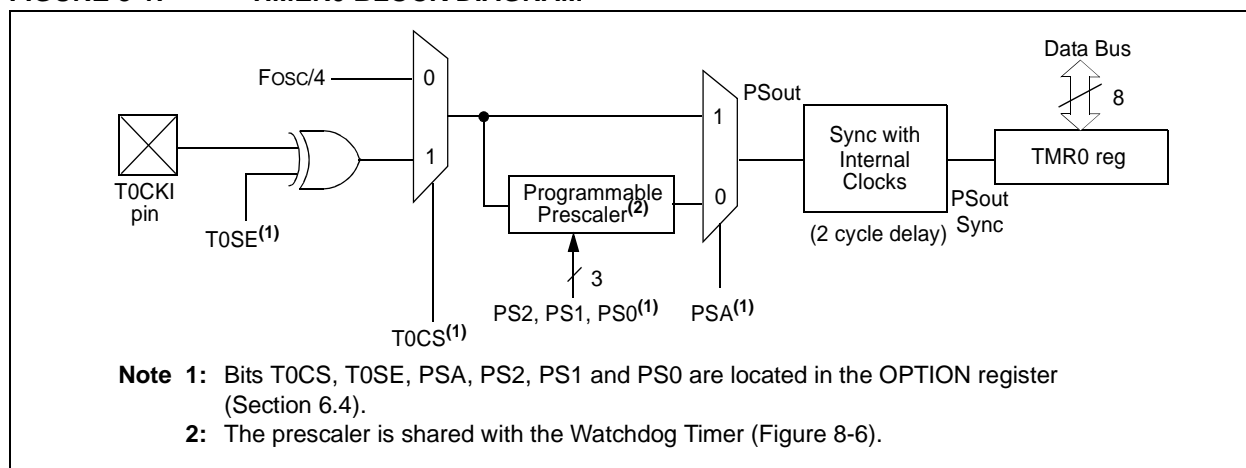
Counter mode is selected by setting the T0CS bit (OPTION<5>). In this mode, Timer0 will increment either on every rising or falling edge of pin T0CKI. The incrementing edge is determined by the source edge select bit T0SE (OPTION<4>). Clearing the T0SE bit selects the rising edge. Restrictions on the external clock input are discussed in detail in Section 8.1.

**Note:** The prescaler may be used by either the Timer0 module or the Watchdog Timer, but not both.

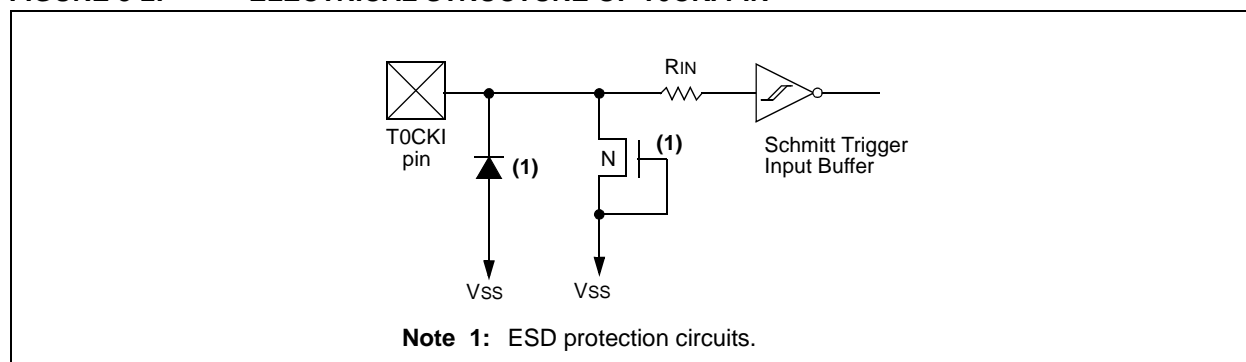
The prescaler assignment is controlled in software by the control bit PSA (OPTION<3>). Clearing the PSA bit will assign the prescaler to Timer0. The prescaler is not readable or writable. When the prescaler is assigned to the Timer0 module, prescale values of 1:2, 1:4,..., 1:256 are selectable. Section 8.2 details the operation of the prescaler.

A summary of registers associated with the Timer0 module is found in Table 8-1.

### FIGURE 8-1: TIMER0 BLOCK DIAGRAM



**FIGURE 8-2: ELECTRICAL STRUCTURE OF T0CKI PIN**



# PIC16C5X

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NOTES:



# PIC16C5X

**TABLE 10-2: INSTRUCTION SET SUMMARY**

Mnemonic, Operands		Description	Cycles	12-Bit Opcode			Status Affected	Notes
				MSb	LSb			
ADDWF	f, d	Add W and f	1	0001	11df	ffff	C, DC, Z	1, 2, 4
ANDWF	f, d	AND W with f	1	0001	01df	ffff	Z	2, 4
CLRF	f	Clear f	1	0000	011f	ffff	Z	4
CLRW	—	Clear W	1	0000	0100	0000	Z	
COMF	f, d	Complement f	1	0010	01df	ffff	Z	
DECF	f, d	Decrement f	1	0000	11df	ffff	Z	2, 4
DECFSZ	f, d	Decrement f, Skip if 0	1 (2)	0010	11df	ffff	None	2, 4
INCF	f, d	Increment f	1	0010	10df	ffff	Z	2, 4
INCFSZ	f, d	Increment f, Skip if 0	1 (2)	0011	11df	ffff	None	2, 4
IORWF	f, d	Inclusive OR W with f	1	0001	00df	ffff	Z	2, 4
MOVF	f, d	Move f	1	0010	00df	ffff	Z	2, 4
MOVWF	f	Move W to f	1	0000	001f	ffff	None	1, 4
NOP	—	No Operation	1	0000	0000	0000	None	
RLF	f, d	Rotate left f through Carry	1	0011	01df	ffff	C	2, 4
RRF	f, d	Rotate right f through Carry	1	0011	00df	ffff	C	2, 4
SUBWF	f, d	Subtract W from f	1	0000	10df	ffff	C, DC, Z	1, 2, 4
SWAPF	f, d	Swap f	1	0011	10df	ffff	None	2, 4
XORWF	f, d	Exclusive OR W with f	1	0001	10df	ffff	Z	2, 4
BIT-ORIENTED FILE REGISTER OPERATIONS								
BCF	f, b	Bit Clear f	1	0100	bbbf	ffff	None	2, 4
BSF	f, b	Bit Set f	1	0101	bbbf	ffff	None	2, 4
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	0110	bbbf	ffff	None	
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	0111	bbbf	ffff	None	
LITERAL AND CONTROL OPERATIONS								
ANDLW	k	AND literal with W	1	1110	kkkk	kkkk	Z	1
CALL	k	Call subroutine	2	1001	kkkk	kkkk	None	
CLRWDT	k	Clear Watchdog Timer	1	0000	0000	0100	TO, PD	
GOTO	k	Unconditional branch	2	101k	kkkk	kkkk	None	
IORLW	k	Inclusive OR Literal with W	1	1101	kkkk	kkkk	Z	
MOVLW	k	Move Literal to W	1	1100	kkkk	kkkk	None	
OPTION	k	Load OPTION register	1	0000	0000	0010	None	
RETLW	k	Return, place Literal in W	2	1000	kkkk	kkkk	None	
SLEEP	—	Go into standby mode	1	0000	0000	0011	TO, PD	
TRIS	f	Load TRIS register	1	0000	0000	0fff	None	3
XORLW	k	Exclusive OR Literal to W	1	1111	kkkk	kkkk	Z	

**Note 1:** The 9th bit of the program counter will be forced to a '0' by any instruction that writes to the PC except for GOTO (see Section 6.5 for more on program counter).

- When an I/O register is modified as a function of itself (e.g. `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.
- The instruction `TRIS f`, where  $f = 5, 6$  or  $7$  causes the contents of the W register to be written to the tristate latches of PORTA, B or C respectively. A '1' forces the pin to a hi-impedance state and disables the output buffers.
- If this instruction is executed on the TMR0 register (and, where applicable,  $d = 1$ ), the prescaler will be cleared (if assigned to TMR0).

## GOTO Unconditional Branch

Syntax: [ *label* ] GOTO *k*

Operands:  $0 \leq k \leq 511$

Operation:  $k \rightarrow PC<8:0>;$   
 $STATUS<6:5> \rightarrow PC<10:9>$

Status Affected: None

Encoding: 

101k	kkkk	kkkk
------	------	------

Description: GOTO is an unconditional branch. The 9-bit immediate value is loaded into PC bits <8:0>. The upper bits of PC are loaded from STATUS<6:5>. GOTO is a two-cycle instruction.

Words: 1

Cycles: 2

Example: GOTO THERE

After Instruction  
PC = address (THERE)

## INCF Increment f

Syntax: [ *label* ] INCF *f,d*

Operands:  $0 \leq f \leq 31$   
 $d \in [0,1]$

Operation:  $(f) + 1 \rightarrow (\text{dest})$

Status Affected: Z

Encoding: 

0010	10df	ffff
------	------	------

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example: INCF CNT, 1

Before Instruction  
CNT = 0xFF  
Z = 0

After Instruction  
CNT = 0x00  
Z = 1

## INCFSZ Increment f, Skip if 0

Syntax: [ *label* ] INCFSZ *f,d*

Operands:  $0 \leq f \leq 31$   
 $d \in [0,1]$

Operation:  $(f) + 1 \rightarrow (\text{dest}), \text{skip if result} = 0$

Status Affected: None

Encoding: 

0011	11df	ffff
------	------	------

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'. If the result is 0, then the next instruction, which is already fetched, is discarded and a NOP is executed instead making it a two-cycle instruction.

Words: 1

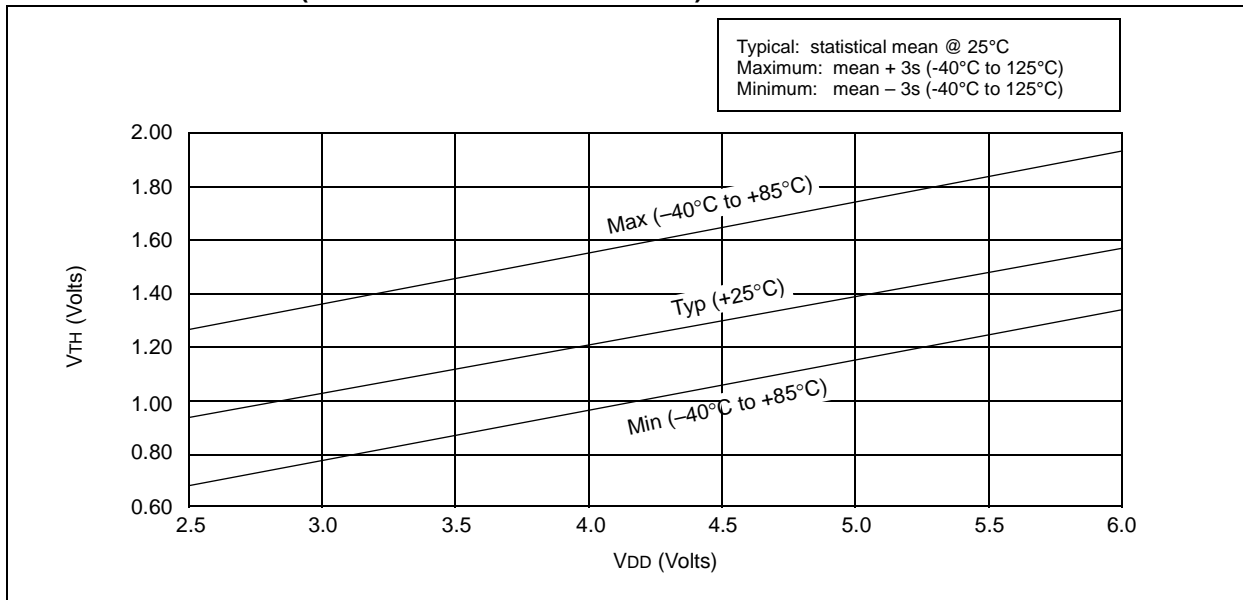
Cycles: 1(2)

Example: HERE INCFSZ CNT, 1  
GOTO LOOP  
CONTINUE •  
•  
•

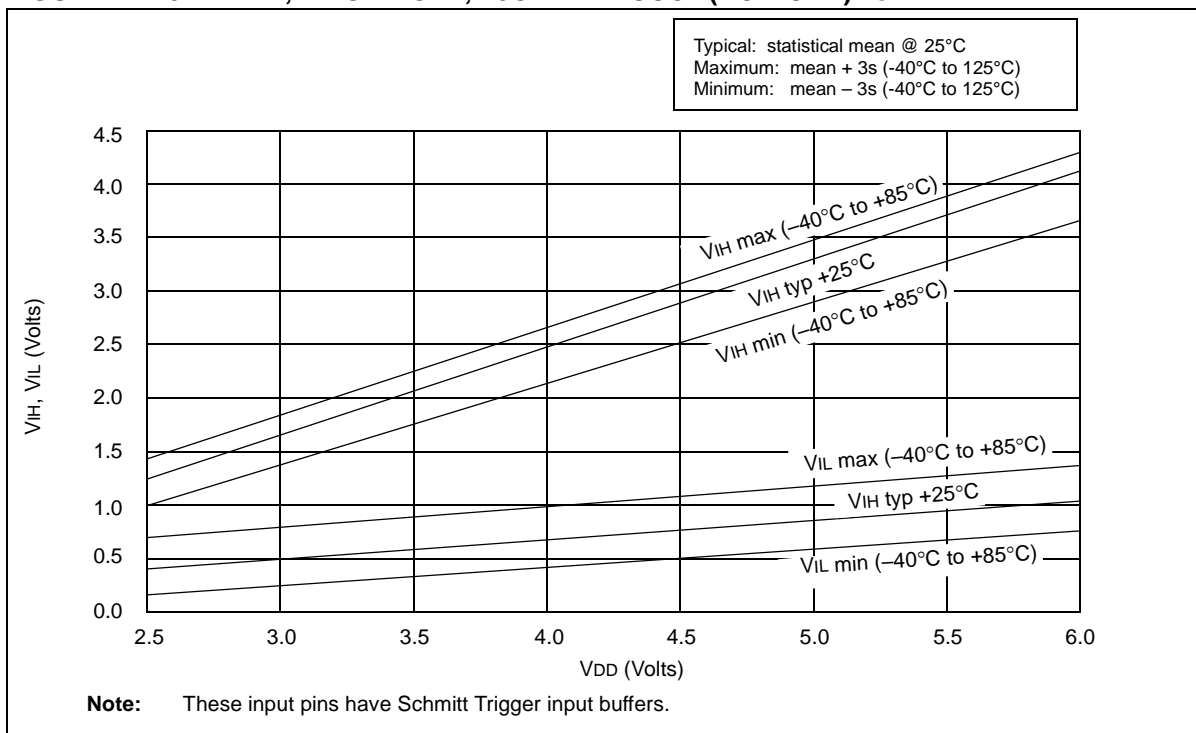
Before Instruction  
PC = address (HERE)

After Instruction  
CNT = CNT + 1;  
if CNT = 0,  
PC = address (CONTINUE);  
if CNT  $\neq$  0,  
PC = address (HERE + 1)

**FIGURE 14-9:  $V_{TH}$  (INPUT THRESHOLD VOLTAGE) OF I/O PINS vs.  $V_{DD}$**



**FIGURE 14-10:  $V_{IH}$ ,  $V_{IL}$  OF MCLR, T0CKI AND OSC1 (RC MODE) vs.  $V_{DD}$**



# PIC16C5X

## 15.2 DC Characteristics: PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
PIC16C54A-04E, 10E, 20E (Extended)		Standard Operating Conditions (unless otherwise specified) Operating Temperature $-40^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ for extended					
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
D001	VDD	<b>Supply Voltage</b>					
		PIC16LC54A	3.0 2.5	— —	6.25 6.25	V V	XT and RC modes LP mode
D001A		PIC16C54A	3.5 4.5	— —	5.5 5.5	V V	RC and XT modes HS mode
D002	VDR	<b>RAM Data Retention Voltage<sup>(1)</sup></b>	—	1.5*	—	V	Device in SLEEP mode
D003	VPOR	<b>VDD Start Voltage</b> to ensure Power-on Reset	—	VSS	—	V	See Section 5.1 for details on Power-on Reset
D004	SVDD	<b>VDD Rise Rate</b> to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset
D010	IDD	<b>Supply Current<sup>(2)</sup></b>					
		PIC16LC54A	—	0.5	25	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC <sup>(3)</sup> and XT modes
			—	11	27	μA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Commercial
			—	11	35	μA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Industrial
			—	11	37	μA	FOSC = 32 kHz, VDD = 2.5V, LP mode, Extended
D010A		PIC16C54A	—	1.8	3.3	mA	FOSC = 4.0 MHz, VDD = 5.5V, RC <sup>(3)</sup> and XT modes
			—	4.8	10	mA	FOSC = 10 MHz, VDD = 5.5V, HS mode
			—	9.0	20	mA	FOSC = 20 MHz, VDD = 5.5V, HS mode

Legend: Rows with standard voltage device data only are shaded for improved readability.

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

**Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

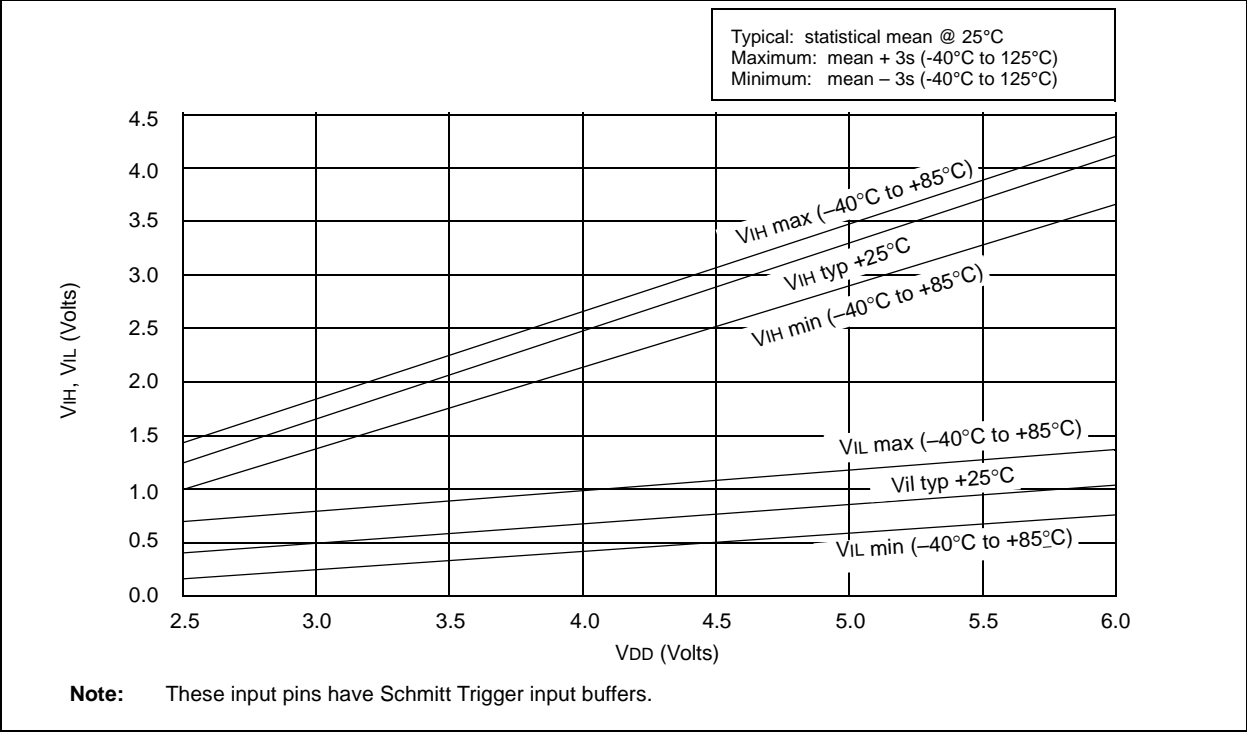
**Note 2:** The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to VSS, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.

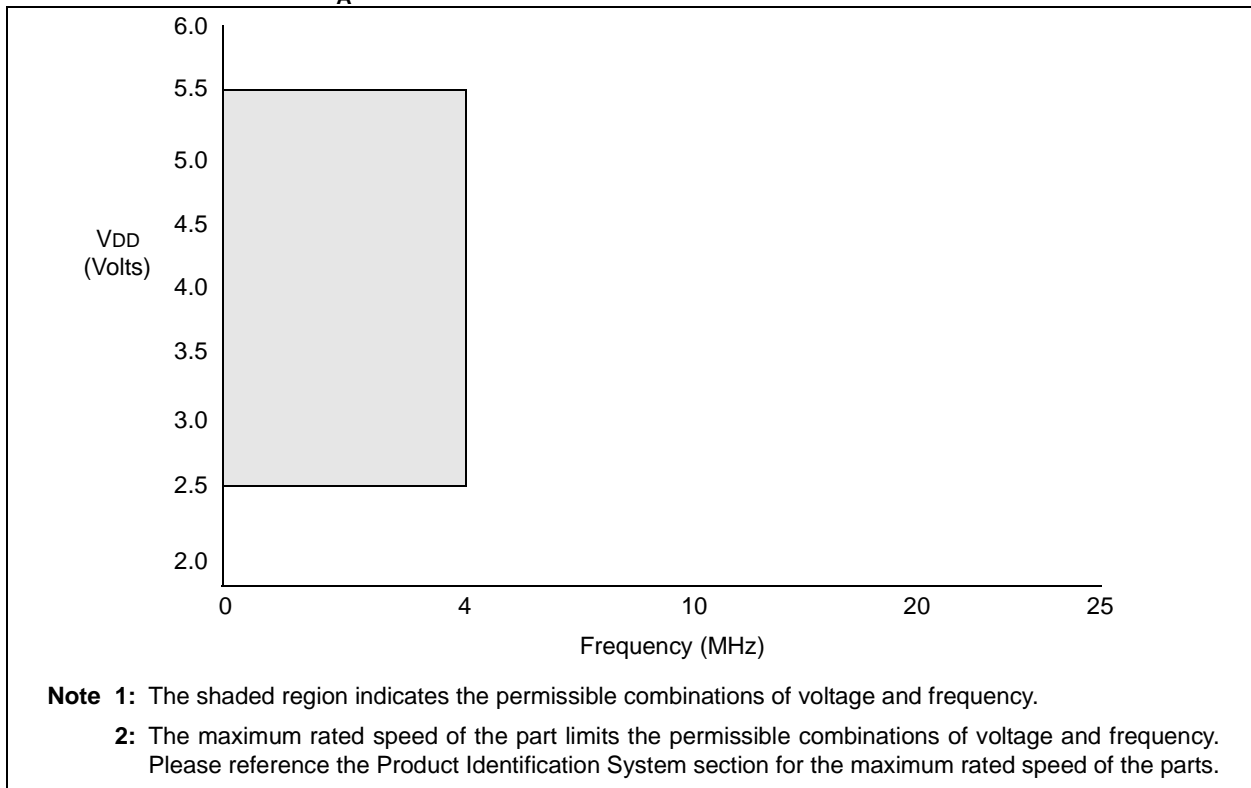
b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.

**Note 3:** Does not include current through REXT. The current through the resistor can be estimated by the formula:  $I_R = V_{DD}/2R_{EXT}$  (mA) with REXT in kΩ.

FIGURE 16-9:  $V_{IH}$ ,  $V_{IL}$  OF  $\overline{MCLR}$ ,  $T0CKI$  AND  $OSC1$  (IN RC MODE) vs.  $V_{DD}$



**FIGURE 17-3: PIC16LC54C/55A/56A/57C/58B VOLTAGE-FREQUENCY GRAPH,  $0^{\circ}\text{C} \leq T_A \leq +85^{\circ}\text{C}$**



**FIGURE 17-4: PIC16LC54C/55A/56A/57C/58B VOLTAGE-FREQUENCY GRAPH,  $-40^{\circ}\text{C} \leq T_A \leq 0^{\circ}\text{C}$**

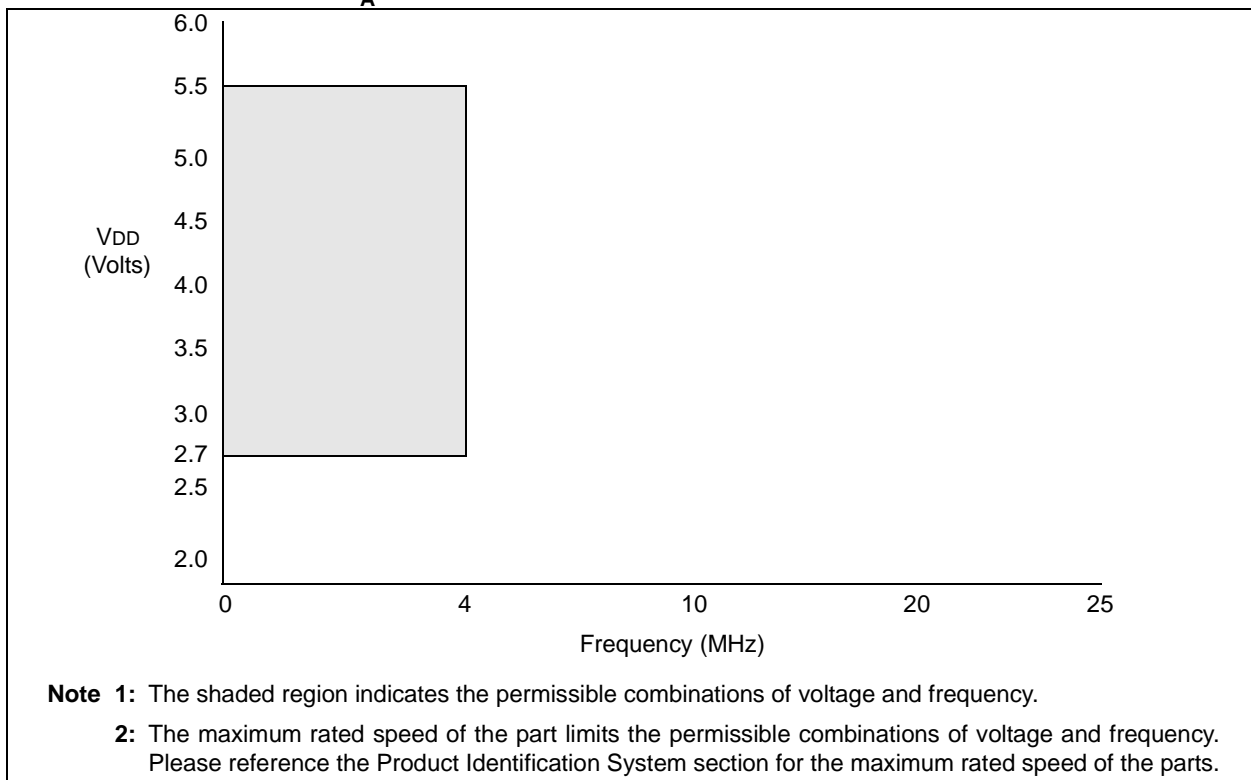


FIGURE 18-10: VTH (INPUT THRESHOLD TRIP POINT VOLTAGE) OF OSC1 INPUT (IN XT, HS AND LP MODES) vs. VDD

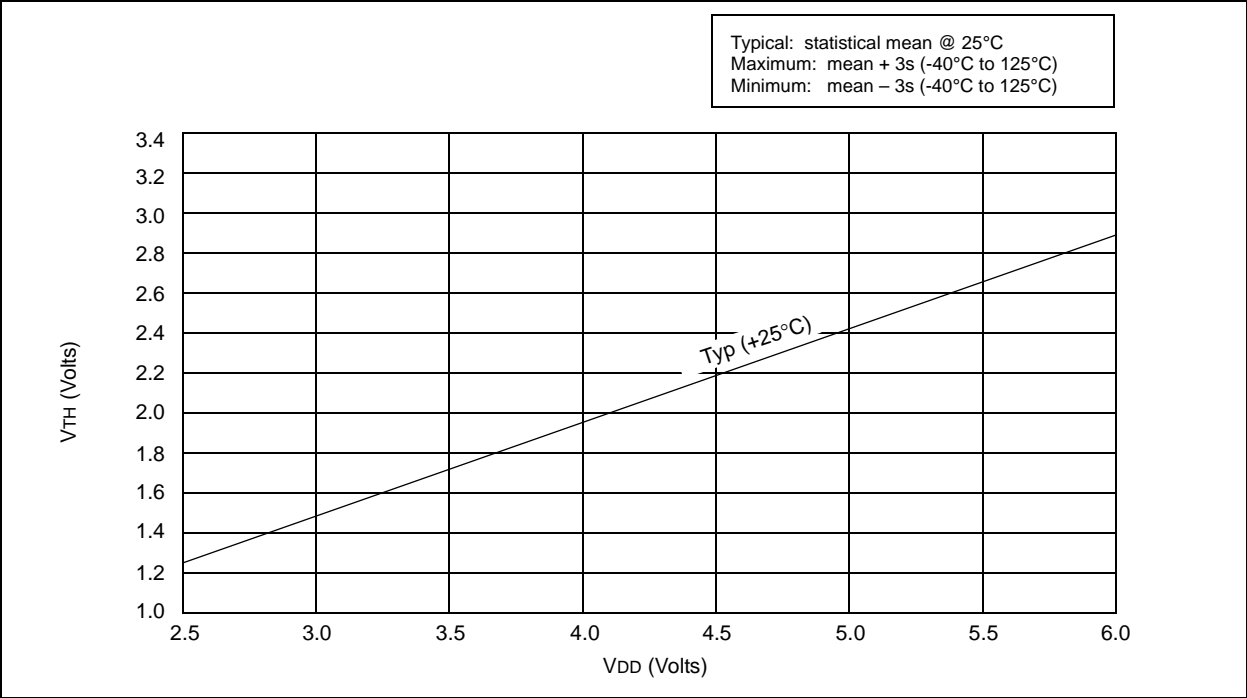
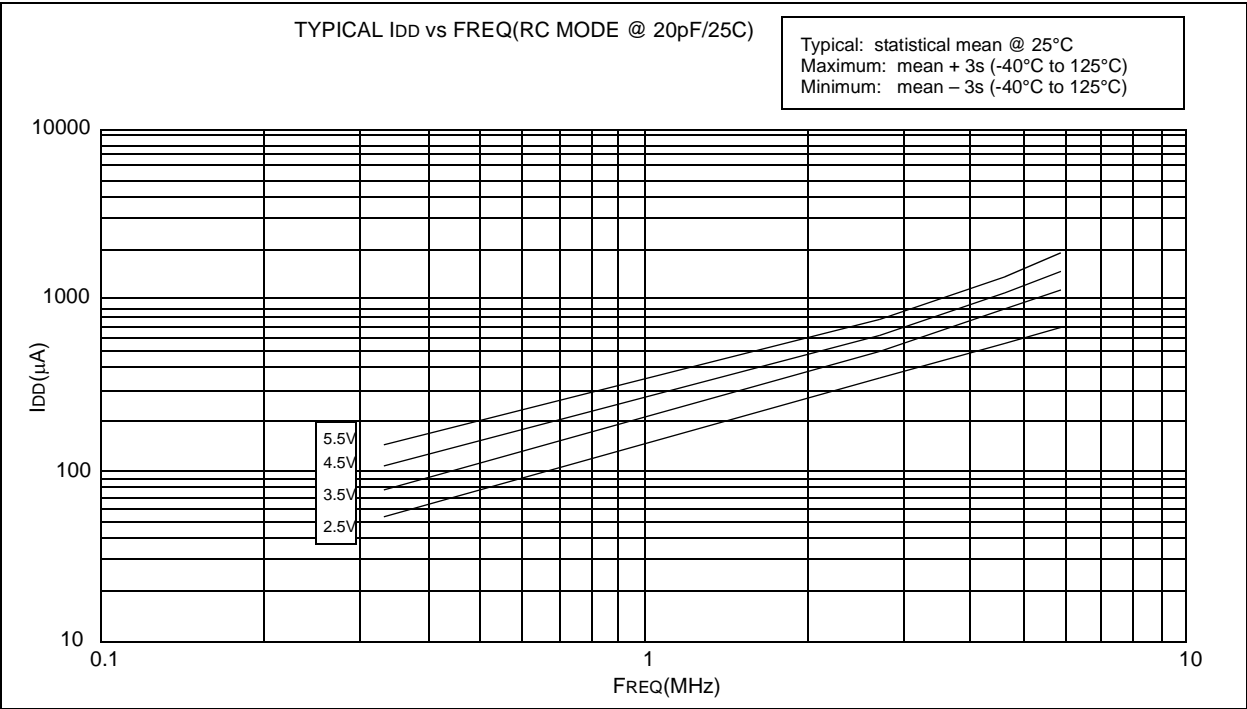


FIGURE 18-11: TYPICAL IDD vs. FREQUENCY (WDT DISABLED, RC MODE @ 20 pF, 25°C)



## 19.0 ELECTRICAL CHARACTERISTICS - PIC16LC54C 40MHz

### Absolute Maximum Ratings<sup>(†)</sup>

Ambient temperature under bias .....	–55°C to +125°C
Storage temperature .....	–65°C to +150°C
Voltage on VDD with respect to VSS .....	0 to +7.5V
Voltage on $\overline{\text{MCLR}}$ with respect to VSS.....	0 to +14V
Voltage on all other pins with respect to VSS .....	–0.6V to (VDD + 0.6V)
Total power dissipation <sup>(1)</sup> .....	800 mW
Max. current out of VSS pin .....	150 mA
Max. current into VDD pin .....	100 mA
Max. current into an input pin (T0CKI only) .....	±500 µA
Input clamp current, I <sub>IK</sub> (V <sub>I</sub> < 0 or V <sub>I</sub> > VDD).....	±20 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0 or V <sub>O</sub> > VDD) .....	±20 mA
Max. output current sunk by any I/O pin .....	25 mA
Max. output current sourced by any I/O pin .....	20 mA
Max. output current sourced by a single I/O (Port A, B or C) .....	50 mA
Max. output current sunk by a single I/O (Port A, B or C).....	50 mA

**Note 1:** Power dissipation is calculated as follows:  $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD} - V_{OH}) \times I_{OH}\} + \sum (V_{OL} \times I_{OL})$

† NOTICE: Stresses above those listed under "Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.



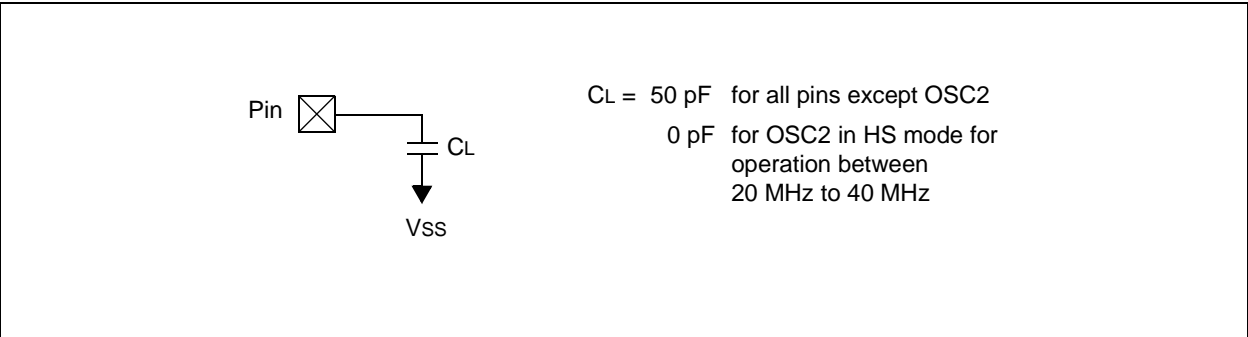
19.3 Timing Parameter Symbolology and Load Conditions

The timing parameter symbols have been created with one of the following formats:

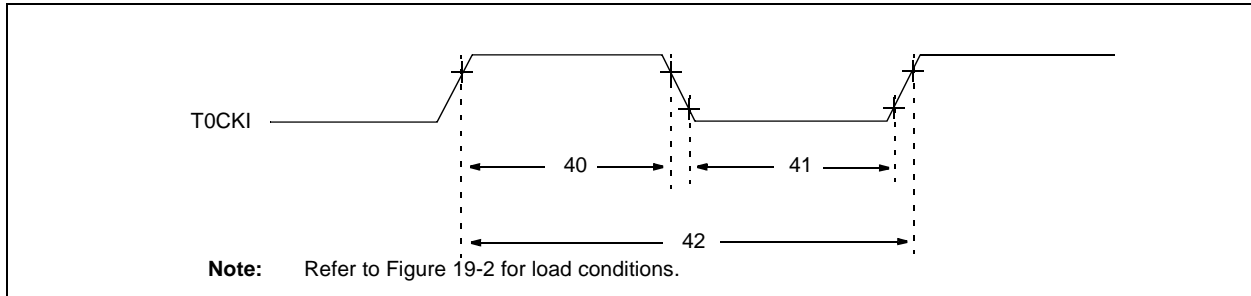
- 1. TppS2ppS
- 2. TppS

T		T	Time
F	Frequency		
Lowercase letters (pp) and their meanings:			
pp		mc	MCLR
2	to	osc	oscillator
ck	CLKOUT	os	OSC1
cy	cycle time	t0	T0CKI
drt	device reset timer	wdt	watchdog timer
io	I/O port		
Uppercase letters and their meanings:			
S		P	Period
F	Fall	R	Rise
H	High	V	Valid
I	Invalid (Hi-impedance)	Z	Hi-impedance
L	Low		

FIGURE 19-2: LOAD CONDITIONS FOR DEVICE TIMING SPECIFICATIONS - PIC16C54C/C55A/C56A/C57C/C58B-40



**FIGURE 19-6: TIMER0 CLOCK TIMINGS - PIC16C5X-40**



**TABLE 19-4: TIMER0 CLOCK REQUIREMENTS PIC16C5X-40**

AC Characteristics			Standard Operating Conditions (unless otherwise specified)				
			Operating Temperature $0^{\circ}\text{C} \leq T_A \leq +70^{\circ}\text{C}$ for commercial				
Param No.	Symbol	Characteristic	Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width - No Prescaler	$0.5 T_{CY} + 20^*$	—	—	ns	
		- With Prescaler	$10^*$	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width - No Prescaler	$0.5 T_{CY} + 20^*$	—	—	ns	
		- With Prescaler	$10^*$	—	—	ns	
42	Tt0P	T0CKI Period	$20 \text{ or } \frac{T_{CY} + 40^*}{N}$	—	—	ns	Whichever is greater. N = Prescale Value (1, 2, 4,..., 256)

\* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 20-2: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (25°C)

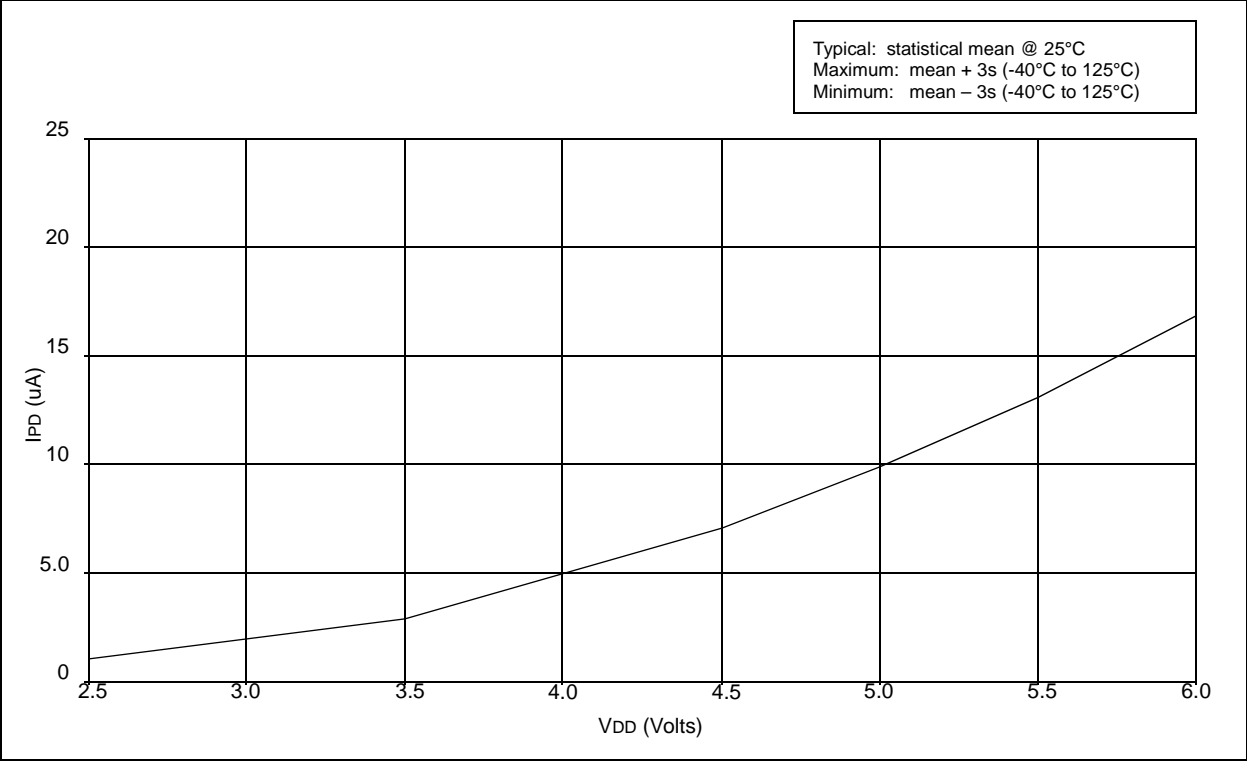
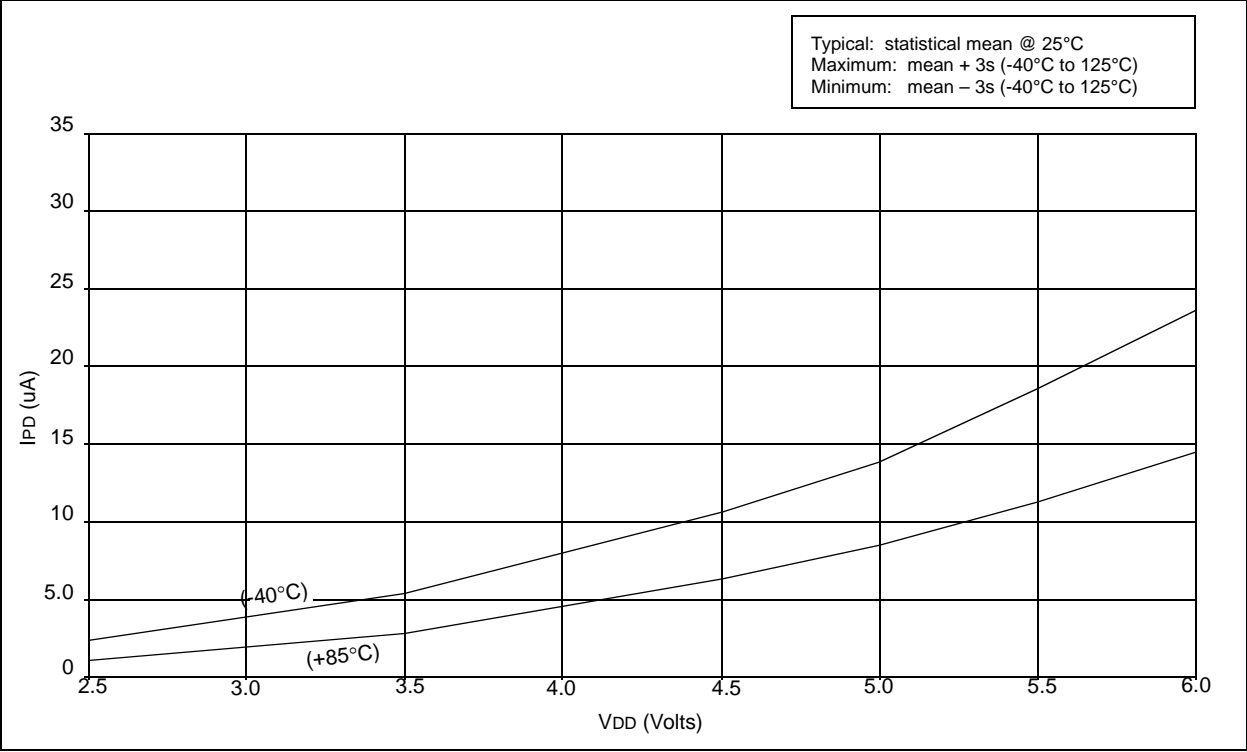


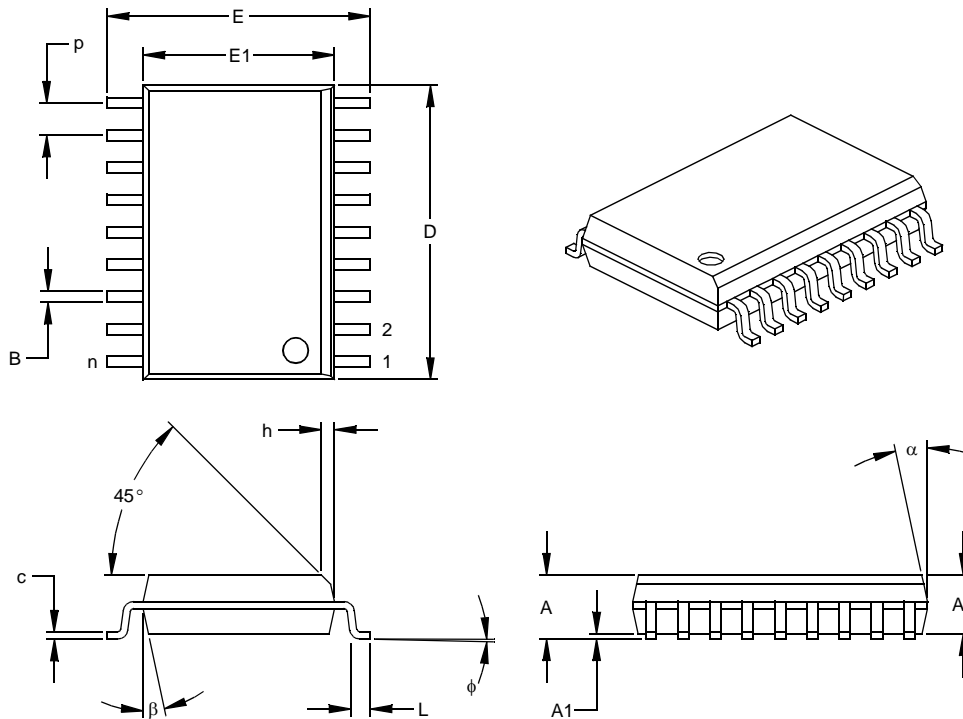
FIGURE 20-3: TYPICAL IPD vs. VDD, WATCHDOG ENABLED (-40°C, 85°C)



# PIC16C5X

## 18-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

**Note:** For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59
Overall Length	D	.446	.454	.462	11.33	11.53	11.73
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle	φ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.012	0.23	0.27	0.30
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

\* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side.

JEDEC Equivalent: MS-013

Drawing No. C04-051

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**Note the following details of the code protection feature on Microchip devices:**

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